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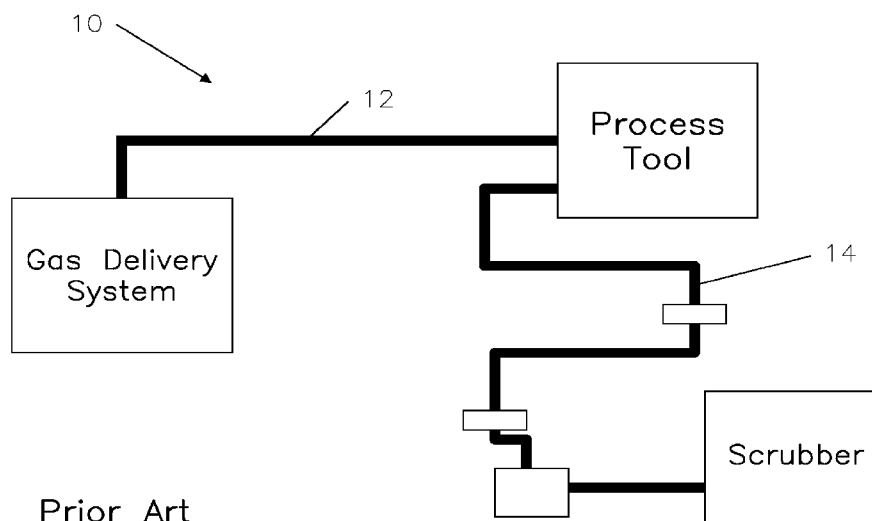


FIG. 1

(57) Abstract: A heater system is provided that includes a hybrid insulation cover that has a first cover disposed around hinged carrier members and heat trace sections, and a second cover operatively engaged with the first cover and adapted for detachable placement around a heating target and its varying geometries. A flexible insulation jacket having a similar construction as the second cover is also provided for use with connector assemblies. Furthermore, a heater system is provided that includes at least one heat trace section encapsulated within adjacent insulating members for use with heating gaslines and pumplines of semiconductor processing systems.